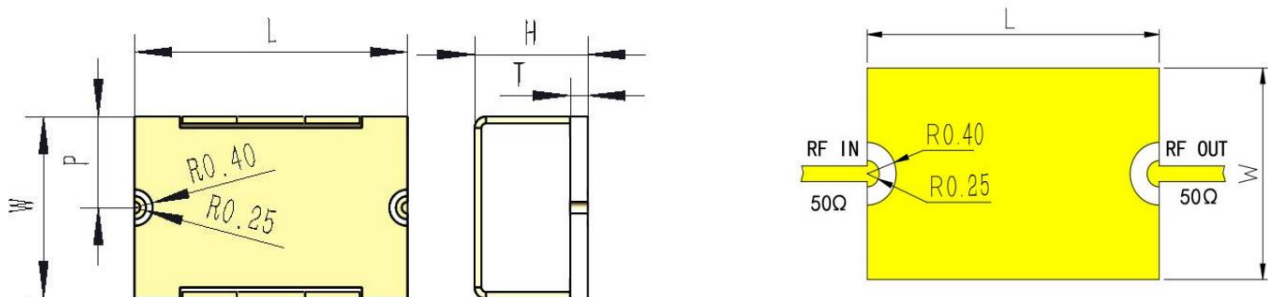


## Electrical Specification

| ITEM |                       | Min           | Max  | Unit |
|------|-----------------------|---------------|------|------|
| 1    | Frequency             | 12            | 14.1 | GHz  |
| 2    | Insertion Loss        |               | 5.8  | dB   |
| 3    | Ripple                |               | 2.3  | dB   |
| 4    | Rejection             | @0.5-10.8GHz  | 60   | dBc  |
|      |                       | @15.5-18GHz   | 60   | dBc  |
| 5    | Return Loss           |               | -12  | dB   |
| 6    | Power Handling        | 1W            |      |      |
| 7    | Storage Temperature   | -55°C ~ +85°C |      |      |
| 8    | Operating Temperature | -40°C ~ +70°C |      |      |
| 9    | Substrate Material    | Ceramic       |      |      |

## Outline Drawing



| L  | W | H   | P | T     |
|----|---|-----|---|-------|
| 12 | 4 | 2.5 | 2 | 0.254 |

Unit: mm

Tolerances: L&W±0.05mm,H±0.2mm

Application Remarks: We have already adopted a solder paste with 240°C melting temperature for the shielding case and internal components. It meets the requirement of 120°C for 1 hour.

## Simulation Curve

